

TLE2061 EMI Immunity Performance

1 EMI Rejection Ratio (EMIRR)

The electromagnetic interference (EMI) rejection ratio, or EMIRR, describes the EMI immunity of operational amplifiers. An adverse effect that is common to many op amps is a change in the offset voltage as a result of RF signal rectification. An op amp that is more efficient at rejecting this change in offset as a result of EMI has a higher EMIRR and is quantified by a decibel value.

Measuring EMIRR can be performed in many ways, but this report provides the EMIRR IN+, which specifically describes the EMIRR performance when the RF signal is applied to the noninverting input pin of the op amp. In general, only the noninverting input is tested for EMIRR for the following three reasons:

1. Op amp input pins are known to be the most sensitive to EMI, and typically rectify RF signals better than the supply or output pins.
2. The noninverting and inverting op amp inputs have symmetrical physical layouts and exhibit nearly matching EMIRR performance.
3. EMIRR is easier to measure on noninverting pins than on other pins because the noninverting input terminal can be isolated on a printed circuit board (PCB). This isolation allows the RF signal to be applied directly to the noninverting input terminal with no complex interactions from other components or connecting PCB traces.

A more formal discussion of the EMIRR IN+ definition and test method is provided in application report [SBOA128, EMI Rejection Ratio of Operational Amplifiers](#), available for download at www.ti.com.

The EMIRR IN+ of the TLE2061 is plotted versus frequency as shown in [Figure 1](#). If available, any dual and quad op amp device versions have nearly similar EMIRR IN+ performance. The TLE2061 unity-gain bandwidth is 1.8 MHz. EMIRR performance below this frequency denotes interfering signals that fall within the op amp bandwidth.

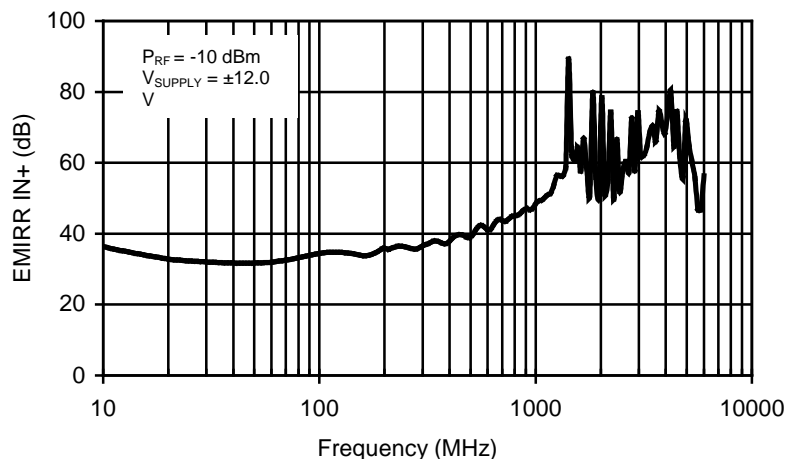


Figure 1. TLE2061 EMIRR IN+ vs Frequency

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Table 1 shows the EMIRR IN+ values for the TLE2061 at particular frequencies commonly encountered in real-world applications. Applications listed in Table 1 may be centered on or operated near the particular frequency shown. This information may be of special interest to designers working with these types of applications, or working in other fields likely to encounter RF interference from broad sources, such as the industrial, scientific, and medical (ISM) radio band.

Table 1. TLE2061 EMIRR IN+ for Frequencies of Interest

| FREQUENCY | APPLICATION/ALLOCATION | EMIRR IN+ |
|-----------|--|-----------|
| 400 MHz | Mobile radio, mobile satellite/space operation, weather, radar, UHF | 37.6 dB |
| 900 MHz | GSM, radio com/nav./GPS (to 1.6 GHz), ISM, aeronautical mobile, UHF | 47.1 dB |
| 1.8 GHz | GSM, mobile personal comm. broadband, satellite, L-band | 50.8 dB |
| 2.4 GHz | 802.11b/g/n, Bluetooth™, mobile personal comm., ISM, amateur radio/satellite, S-band | 66.6 dB |
| 3.6 GHz | Radiolocation, aero comm./nav., satellite, mobile, S-band | 66.1 dB |
| 5.0 GHz | 802.11a/n, aero comm./nav., mobile comm., space/satellite operation, C-band | 71.9 dB |

2 EMIRR IN+ Test Configuration

Figure 2 shows the circuit configuration for testing the EMIRR IN+. An RF source is connected to the op amp noninverting input terminal using a transmission line. The op amp is configured in a unity gain buffer topology with the output connected to a low-pass filter (LPF) and a digital multimeter (DMM). Note that a large impedance mismatch at the op amp input causes a voltage reflection; however, this effect is characterized and accounted for when determining the EMIRR IN+. The resulting dc offset voltage is sampled and measured by the multimeter. The LPF isolates the multimeter from residual RF signals that may interfere with multimeter accuracy. Refer to [SBOA128](#) for more details.

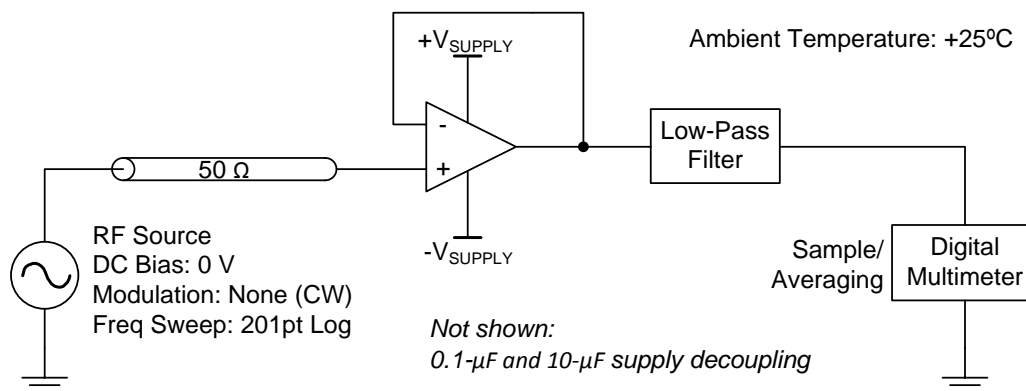


Figure 2. EMIRR IN+ Test Configuration Schematic

References

1. Chris Hall and Thomas Kuehl, “[EMI Rejection Ratio of Operational Amplifiers](#),” application report [SBOA128](#), Texas Instruments, August 2011.
2. Gerrit de Wagt and Arie van Staveren, “[A Specification for EMI Hardened Operational Amplifiers](#),” application report [SNOA497A](#), Texas Instruments, January 2010.

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